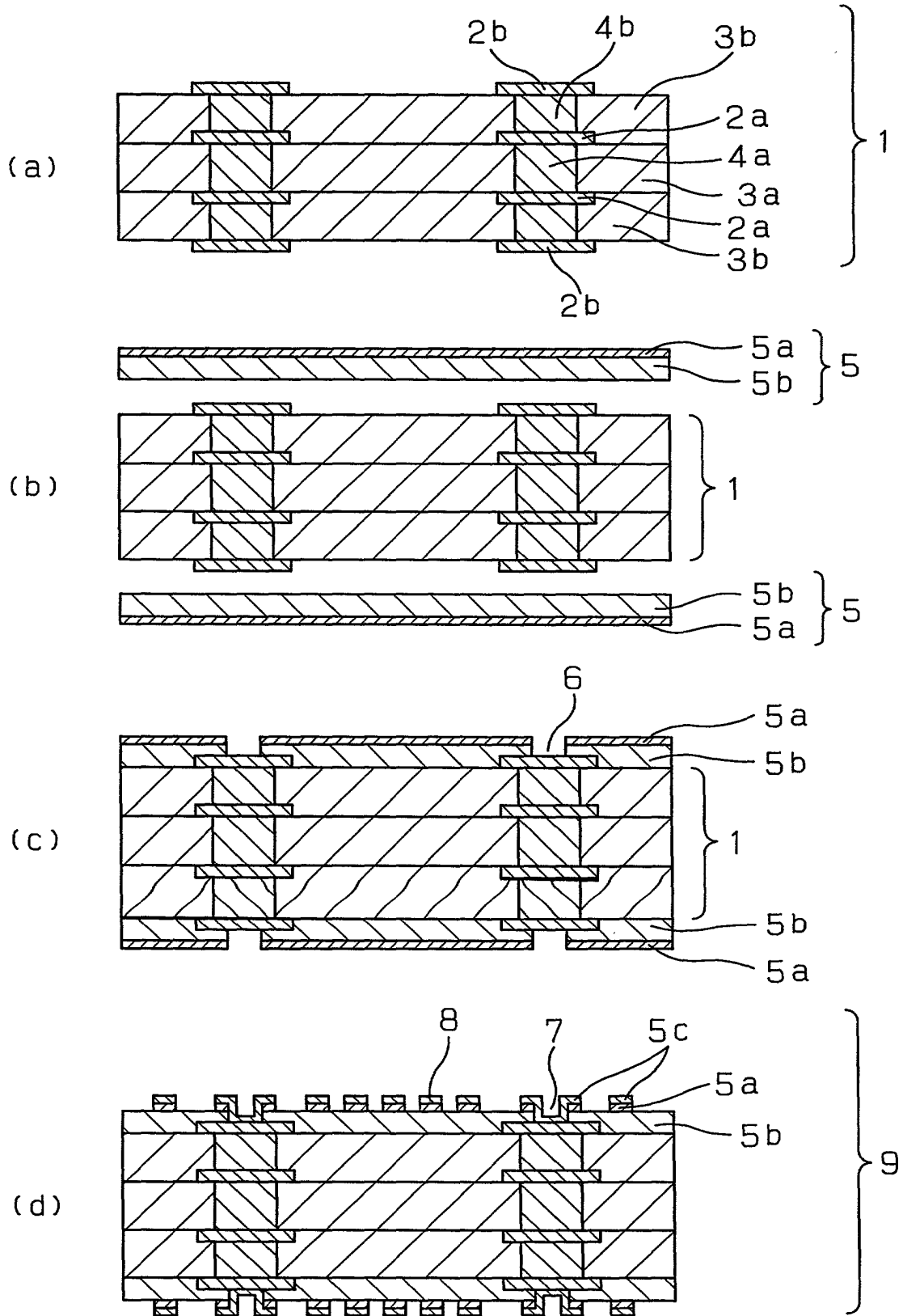
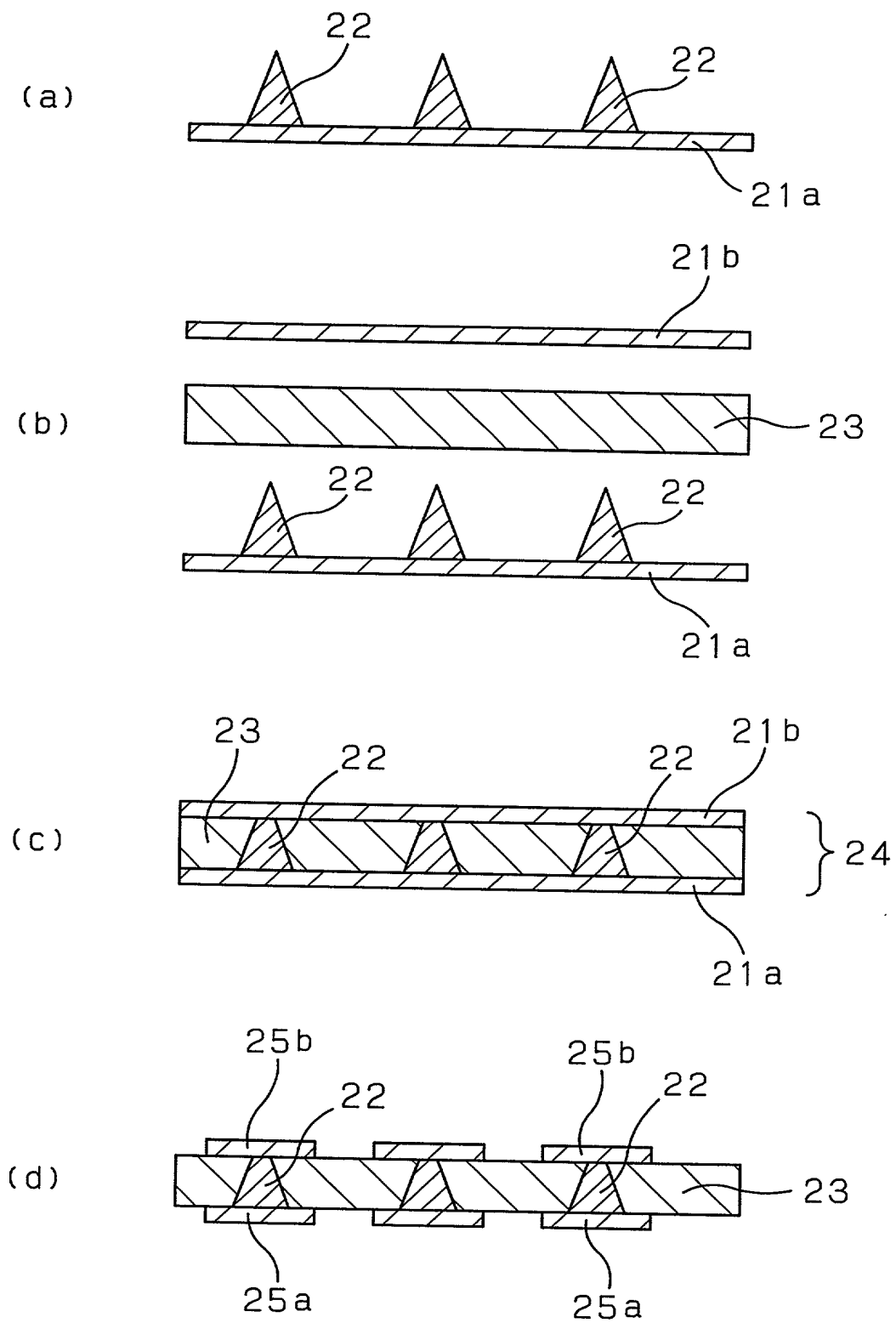
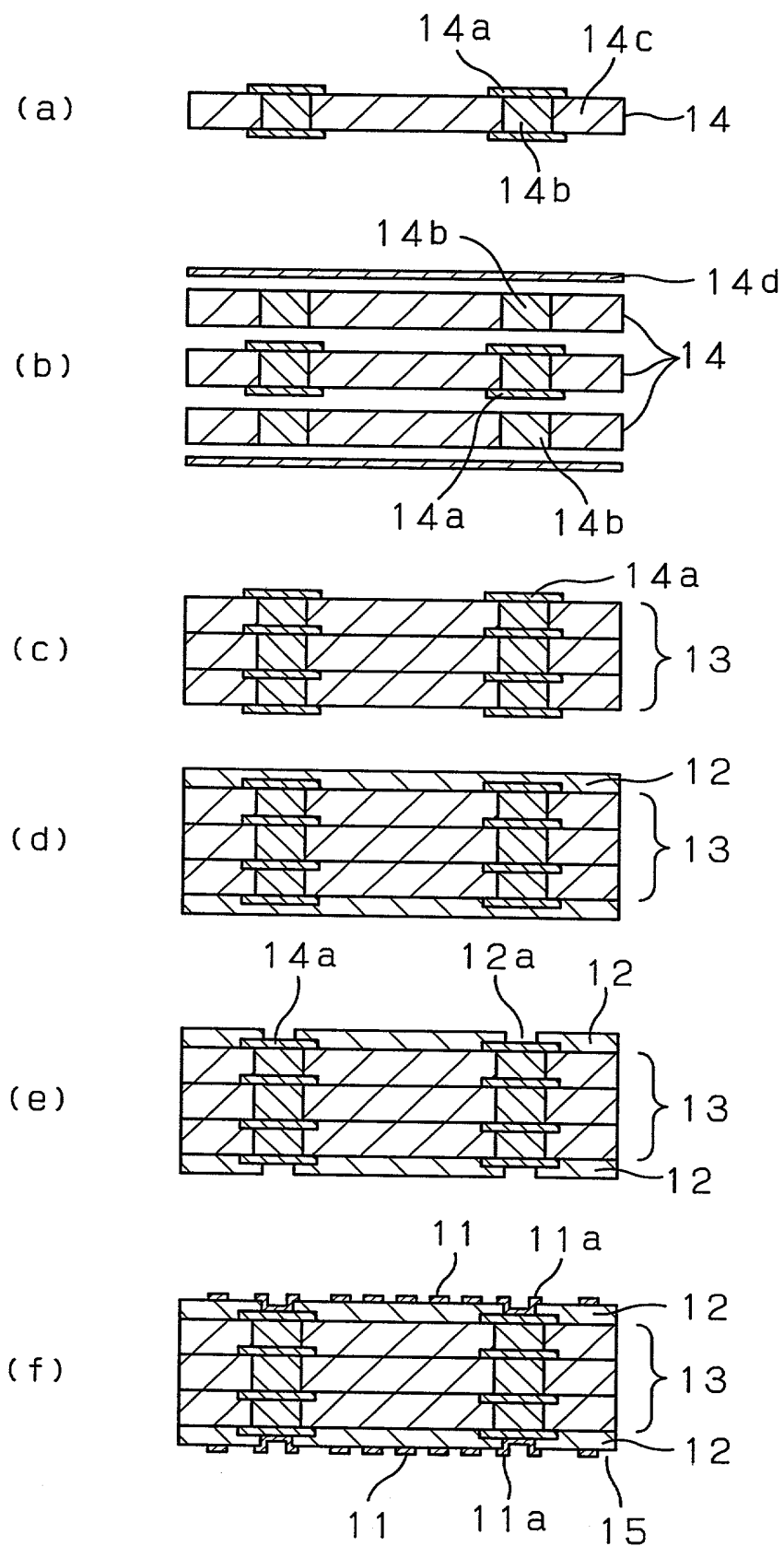


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Fig. 1

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Fig. 2

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Fig. 3



Key to Reference Alphanumeric Characters

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	1	Inner Layer Material
	2	Inner Conductive Pattern
	2a	First Inner Conductive Pattern
10	2b	Second Inner Conductive Pattern
	3	Insulating Substrate for Inner Layer Material
	3a	First Insulating Substrate
	3b	Second Insulating Substrate
	4	Conductive Paste and Interstitial Via Hole
15	4a	First Conductive Paste, Interstitial Via Hole
	4b	Second Conductive Paste, Interstitial Via Hole
	5	Metal Foil with Insulating Resin
	5a	Metal Foil
	5b	Insulating Resin
20	5c	Metal Plating Layer
	6	Non-through Hole
	7	Surface Via Hole (SVH) with Metal Plating Applied to Non-through Hole
	8	Outer Conductive Pattern
25	9	Multilayer Printed Wiring Board
	21a	First Copper Foil
	21b	Second Copper Foil
	22	Conductor Projection
	23	Aramid Nonwoven Fabric Base Material Epoxy Resin Prepreg
30	24	Laminated Board for Inner Layer

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- 25 Inner Conductor Circuit
- 25a First Inner Conductor Circuit, First Inner Conductive Pattern
- 25b Second Inner Conductor Circuit, Second Inner Conductive Pattern